

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6701A/BxxxMR-G
Typical Mass: 16 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.617	Silicon	38500	7440-21-3
Leadframe	5.503	Copper	343900	7440-50-8
	0.022	Tin	1400	7440-31-5
	0.021	Zinc	1300	7440-66-6
	0.024	Chromium	1500	7440-47-3
	0.325	Silver	20300	7440-22-4
Die attach	0.049	Silver	3100	7440-22-4
	0.009	Epoxy	600	—
Bonding wire	0.030	Gold	1900	7440-57-5
Resin	7.356	Silica	459700	60676-86-0
	0.699	Epoxy resin	43700	—
	0.588	Phenol resin	36700	—
	0.418	Metal hydroxide	26100	—
Plating	0.340	Tin	21300	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."